In the Title:

Please change the Title of the application from --Electrical Connector with Strain Relief-- to "Self-Centering Connector with Hold Down".

In the Claims:

Please cancel claims 6 and 37.

Please amend the claims to appear as follows:

B1 SUB C1

1. An electrical connector, mountable to a substrate and comprising:

a housing;

a surface mount contact secured to said housing and adapted to surface mount to a pad on the substrate; and

a non-surface mount hold down secured to said housing and adapted to mount to a hole in the substrate so as to permit said surface mount contact to center on said pad upon mounting to the substrate, wherein said non-surface mount hold down is adapted to retain said housing a distance from a surface of the substrate.

B2 SUB C2

9. A ball grid array connector mountable to a substrate, comprising:

a housing;

a plurality of contacts within said housing;

B2 cncld. sub C3 cncld.

a plurality of fusible elements secured to said contacts for mounting to pads on the substrate; and

a hold down adapted to enter the substrate so as to permit said fusible elements to center on the pads upon mounting to the substrate, wherein said hold down is secured to said housing, and wherein said hold down is adapted to limit flattening of said fusible elements during a reflow process.

B3 sub C3

15. A method of mounting an electrical connector to a substrate, comprising:

providing an electrical connector having a contact and a hold down;

providing a substrate having a pad;

securing said contact to said pad on said substrate;

placing said hold down into said substrate so as to permit said contact to center on said pad upon mounting to the substrate; and

securing said hold down to said substrate, wherein said hold down is adapted to limit flattening of said contact during a reflow process.

B4 sub C4

25. An electrical connector mountable to a substrate, comprising:

a housing having a mounting end facing the substrate;

a plurality of contacts secured to said housing;

a plurality of fusible elements, each secured to a respective one of said plurality of contacts; and

a standoff extending a distance from said mounting end of said housing, wherein said standoff enters the substrate so as to permit said fusible elements to center on pads upon mounting to the substrate, and wherein said standoff is adapted to limit flattening of said fusible elements during a reflow process.

B5 SUB C5

31. In a ball grid array connector mountable to a substrate, wherein the improvement comprises a hold down adapted to enter an opening in the substrate, so as to permit fusible elements on the ball grid array to center on pads on the substrate upon mounting to the substrate, and wherein said hold down is adapted to limit flattening of said fusible elements during a reflow process.

B6 SUB C6

39. An electrical connector, mountable to a substrate and comprising

a housing;

a surface mount contact secured to said housing and adapted to surface mount to a pad on the substrate; and

a non-surface mount hold down secured to said housing and adapted to mount to a hole in the substrate so as to allow relative movement between said connector and said substrate during a reflow process, wherein said non-surface mount hold down is adapted to limit flattening of said surface mount contact during a reflow process.

40. An electrical connector, mountable to a substrate and comprising

a housing;

a surface mount contact secured to said housing and adapted to surface mount to a pad on the substrate; and

a non-surface mount hold down secured to said housing and adapted to mount to a hole in the substrate, wherein said hole has a perimeter larger than a perimeter of said hold down, and wherein said non-surface mount hold down is adapted to limit flattening of said surface mount contact during a reflow process.